

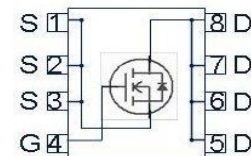
OptiMOS™ Power-Transistor

Features

- Optimized for high performance SMPS, e.g. sync. rec.
- 100% avalanche tested
- Superior thermal resistance
- N-channel
- Qualified according to JEDEC¹⁾ for target applications
- Pb-free lead plating; RoHS compliant
- Halogen-free according to IEC61249-2-21

Product Summary

| | | |
|------------------|-----|----|
| V_{DS} | 60 | V |
| $R_{DS(on),max}$ | 9.7 | mΩ |
| I_D | 46 | A |
| Q_{OSS} | 14 | nC |
| $Q_G(0V..10V)$ | 12 | nC |


PG-TDSON-8


| Type | Package | Marking |
|-------------|------------|----------|
| BSC097N06NS | PG-TDSON-8 | 097N06NS |

Maximum ratings, at $T_j=25\text{ °C}$, unless otherwise specified

| Parameter | Symbol | Conditions | Value | Unit |
|--|---------------|--|-------|------|
| Continuous drain current | I_D | $V_{GS}=10\text{ V}, T_C=25\text{ °C}$ | 46 | A |
| | | $V_{GS}=10\text{ V}, T_C=100\text{ °C}$ | 29 | |
| | | $V_{GS}=10\text{ V}, T_C=25\text{ °C}, R_{thJA}=50\text{K/W}^2)$ | 12 | |
| Pulsed drain current ³⁾ | $I_{D,pulse}$ | $T_C=25\text{ °C}$ | 184 | |
| Avalanche energy, single pulse ⁴⁾ | E_{AS} | $I_D=30\text{ A}, R_{GS}=25\text{ Ω}$ | 13 | mJ |
| Gate source voltage | V_{GS} | | ±20 | V |

¹⁾ J-STD20 and JESD22

²⁾ Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm² (one layer, 70 μm thick) copper area for drain connection. PCB is vertical in still air.

³⁾ See figure 3 for more detailed information

⁴⁾ See figure 13 for more detailed information

Maximum ratings, at $T_j=25\text{ °C}$, unless otherwise specified

| Parameter | Symbol | Conditions | Value | Unit |
|-------------------------------------|-----------------------|--|-------------|------|
| Power dissipation | P_{tot} | $T_C=25\text{ °C}$ | 36 | W |
| | | $T_A=25\text{ °C}$, $R_{\text{thJA}}=50\text{ K/W}^2)$ | 2.5 | |
| Operating and storage temperature | T_j, T_{stg} | | -55 ... 150 | °C |
| IEC climatic category; DIN IEC 68-1 | | | 55/150/56 | |

| Parameter | Symbol | Conditions | Values | | | Unit |
|-----------|--------|------------|--------|------|------|------|
| | | | min. | typ. | max. | |

Thermal characteristics

| | | | | | | |
|-------------------------------------|-------------------|--|---|---|-----|-----|
| Thermal resistance, junction - case | R_{thJC} | bottom | - | - | 3.5 | K/W |
| | | top | - | - | 20 | |
| Device on PCB | R_{thJA} | 6 cm ² cooling area ²⁾ | - | - | 50 | |

Electrical characteristics, at $T_j=25\text{ °C}$, unless otherwise specified

Static characteristics

| | | | | | | |
|----------------------------------|-----------------------------|---|-----|------|------|---------------|
| Drain-source breakdown voltage | $V_{(\text{BR})\text{DSS}}$ | $V_{\text{GS}}=0\text{ V}$, $I_{\text{D}}=1\text{ mA}$ | 60 | - | - | V |
| Gate threshold voltage | $V_{\text{GS(th)}}$ | $V_{\text{DS}}=V_{\text{GS}}$, $I_{\text{D}}=14\text{ }\mu\text{A}$ | 2.1 | 2.8 | 3.3 | |
| Zero gate voltage drain current | I_{DSS} | $V_{\text{DS}}=60\text{ V}$, $V_{\text{GS}}=0\text{ V}$, $T_j=25\text{ °C}$ | - | 0.1 | 1 | μA |
| | | $V_{\text{DS}}=60\text{ V}$, $V_{\text{GS}}=0\text{ V}$, $T_j=125\text{ °C}$ | - | 10 | 100 | |
| Gate-source leakage current | I_{GSS} | $V_{\text{GS}}=20\text{ V}$, $V_{\text{DS}}=0\text{ V}$ | - | 10 | 100 | nA |
| Drain-source on-state resistance | $R_{\text{DS(on)}}$ | $V_{\text{GS}}=10\text{ V}$, $I_{\text{D}}=40\text{ A}$ | - | 8.0 | 9.7 | m Ω |
| | | $V_{\text{GS}}=6\text{ V}$, $I_{\text{D}}=10\text{ A}$ | - | 12.0 | 14.6 | |
| Gate resistance | R_{G} | | - | 1.1 | 1.7 | Ω |
| Transconductance | g_{fs} | $ V_{\text{DS}} >2 I_{\text{D}} R_{\text{DS(on)max}}$, $I_{\text{D}}=40\text{ A}$ | 24 | 48 | - | S |

| Parameter | Symbol | Conditions | Values | | | Unit |
|-----------|--------|------------|--------|------|------|------|
| | | | min. | typ. | max. | |

Dynamic characteristics

| | | | | | | |
|------------------------------|--------------|--|---|-----|------|----|
| Input capacitance | C_{iss} | $V_{GS}=0\text{ V}, V_{DS}=30\text{ V}, f=1\text{ MHz}$ | - | 860 | 1075 | pF |
| Output capacitance | C_{oss} | | - | 210 | 263 | |
| Reverse transfer capacitance | C_{rss} | | - | 16 | 32 | |
| Turn-on delay time | $t_{d(on)}$ | $V_{DD}=30\text{ V}, V_{GS}=10\text{ V}, I_D=40\text{ A}, R_{G,ext,ext}=1.6\ \Omega$ | - | 6 | - | ns |
| Rise time | t_r | | - | 2 | - | |
| Turn-off delay time | $t_{d(off)}$ | | - | 10 | - | |
| Fall time | t_f | | - | 2 | - | |

Gate Charge Characteristics⁵⁾

| | | | | | | |
|------------------------------|---------------|---|---|-----|-----|----|
| Gate to source charge | Q_{gs} | $V_{DD}=30\text{ V}, I_D=40\text{ A}, V_{GS}=0\text{ to }10\text{ V}$ | - | 4.5 | - | nC |
| Gate charge at threshold | $Q_{g(th)}$ | | - | 2.4 | - | |
| Gate to drain charge | Q_{gd} | | - | 2.6 | 3.7 | |
| Switching charge | Q_{sw} | | - | 4.7 | - | |
| Gate charge total | Q_g | | - | 12 | 15 | |
| Gate plateau voltage | $V_{plateau}$ | | - | 5.2 | - | |
| Gate charge total, sync. FET | $Q_{g(sync)}$ | $V_{DS}=0.1\text{ V}, V_{GS}=0\text{ to }10\text{ V}$ | - | 10 | - | nC |
| Output charge | Q_{oss} | $V_{DD}=30\text{ V}, V_{GS}=0\text{ V}$ | - | 14 | - | |

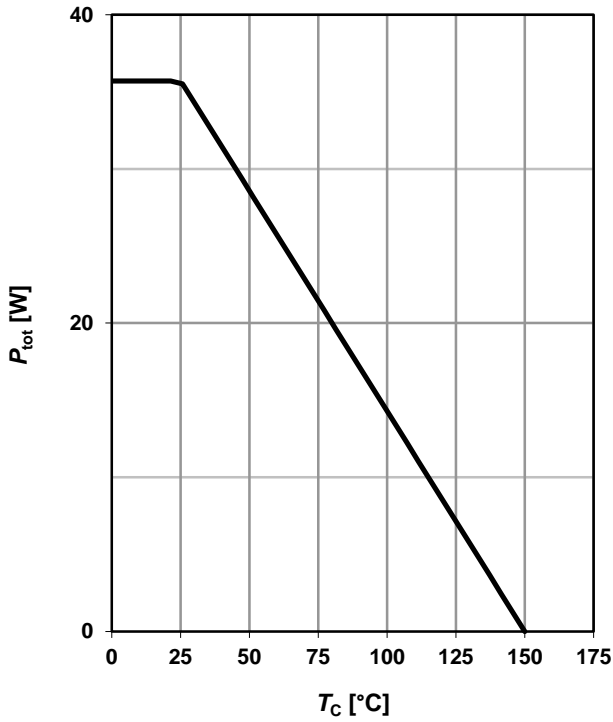
Reverse Diode

| | | | | | | |
|----------------------------------|---------------|--|---|-----|-----|----|
| Diode continuous forward current | I_S | $T_C=25\text{ }^\circ\text{C}$ | - | - | 30 | A |
| Diode pulse current | $I_{S,pulse}$ | | - | - | 184 | |
| Diode forward voltage | V_{SD} | $V_{GS}=0\text{ V}, I_F=30\text{ A}, T_j=25\text{ }^\circ\text{C}$ | - | 1.0 | 1.2 | V |
| Reverse recovery time | t_{rr} | $V_R=30\text{ V}, I_F=30\text{ A}, di_F/dt=100\text{ A}/\mu\text{s}$ | - | 33 | 53 | ns |
| Reverse recovery charge | Q_{rr} | | - | 30 | - | |

⁵⁾ See figure 16 for gate charge parameter definition

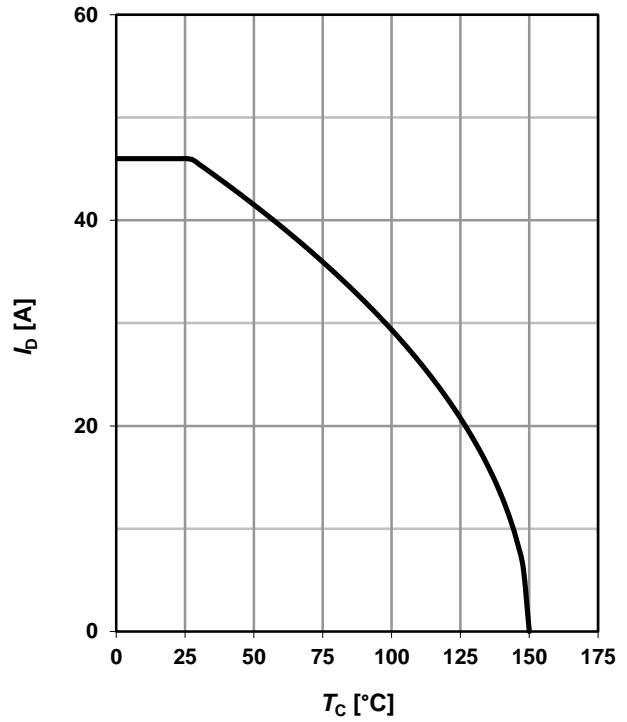
1 Power dissipation

$P_{tot}=f(T_C)$



2 Drain current

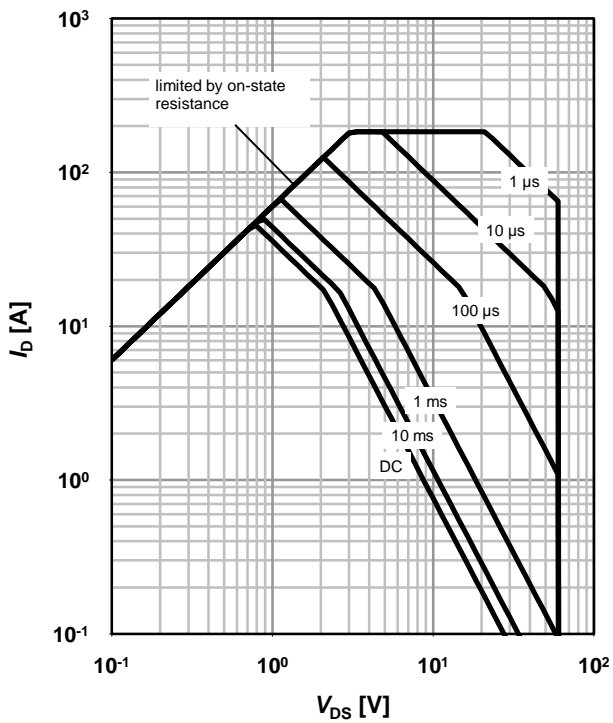
$I_D=f(T_C); V_{GS} \geq 10\text{ V}$



3 Safe operating area

$I_D=f(V_{DS}); T_C=25\text{ °C}; D=0$

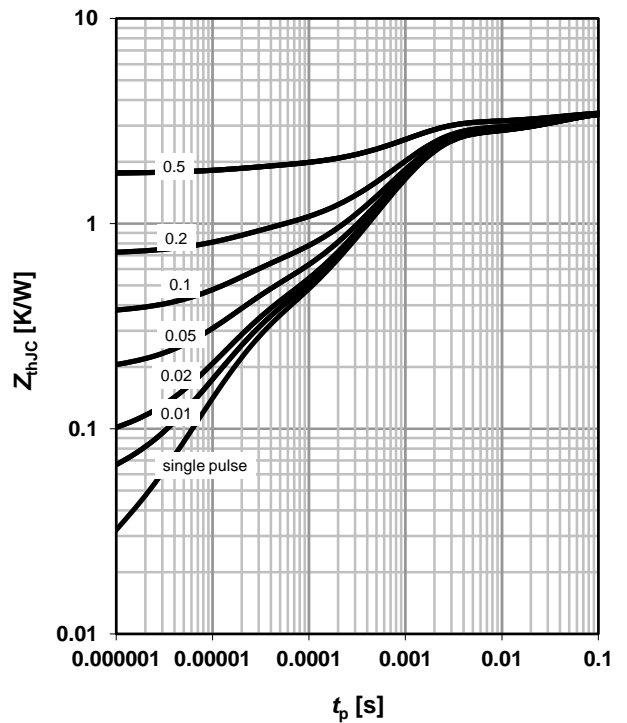
parameter: t_p



4 Max. transient thermal impedance

$Z_{thJC}=f(t_p)$

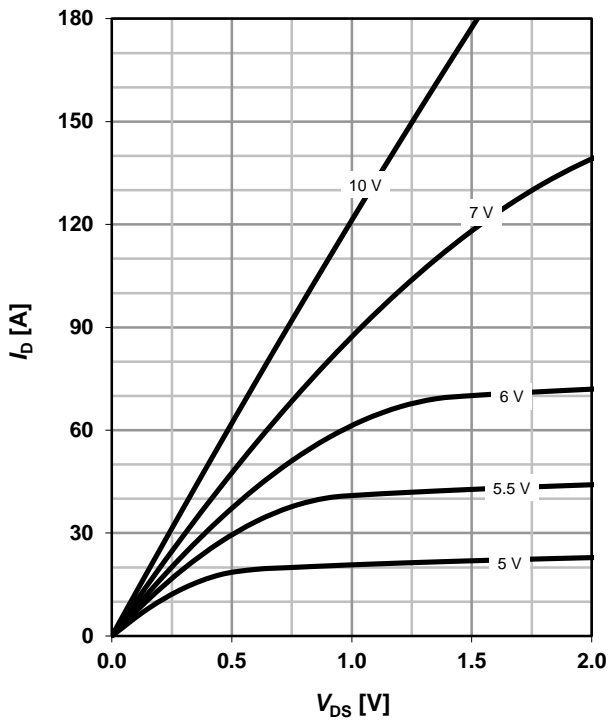
parameter: $D=t_p/T$



5 Typ. output characteristics

$I_D = f(V_{DS}); T_j = 25\text{ °C}$

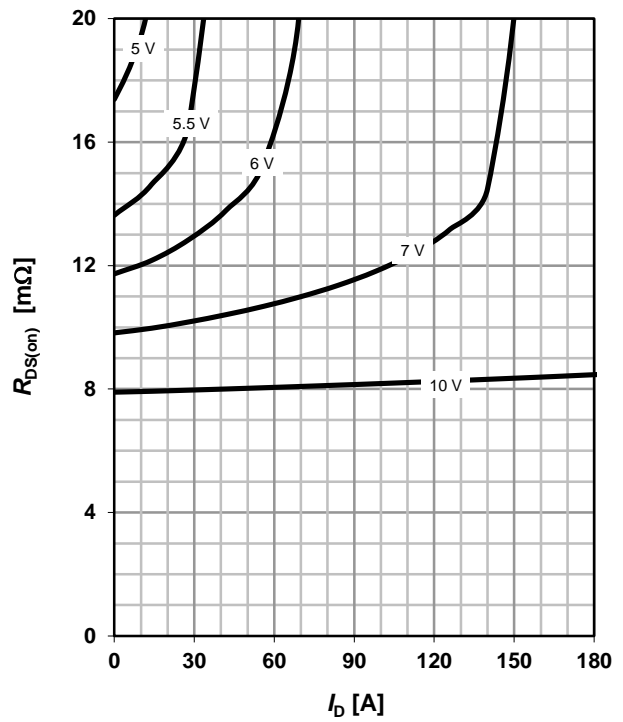
parameter: V_{GS}



6 Typ. drain-source on resistance

$R_{DS(on)} = f(I_D); T_j = 25\text{ °C}$

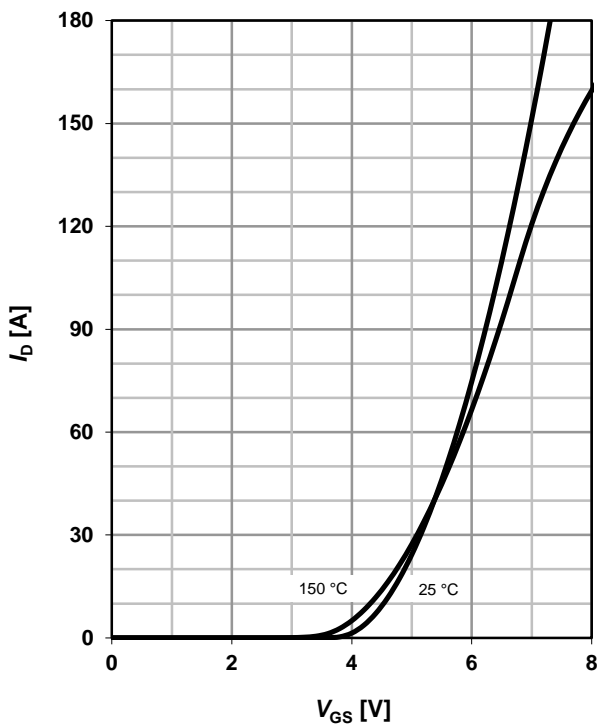
parameter: V_{GS}



7 Typ. transfer characteristics

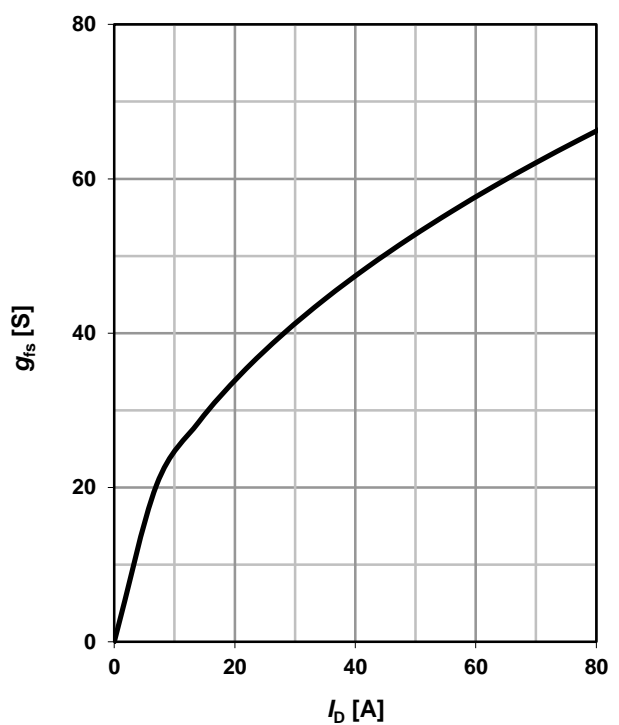
$I_D = f(V_{GS}); |V_{DS}| > 2|I_D|R_{DS(on)max}$

parameter: T_j



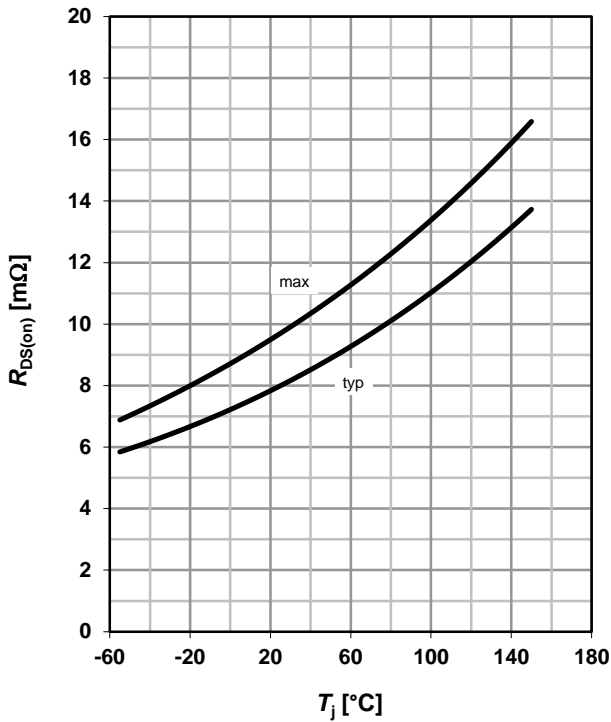
8 Typ. forward transconductance

$g_{fs} = f(I_D); T_j = 25\text{ °C}$



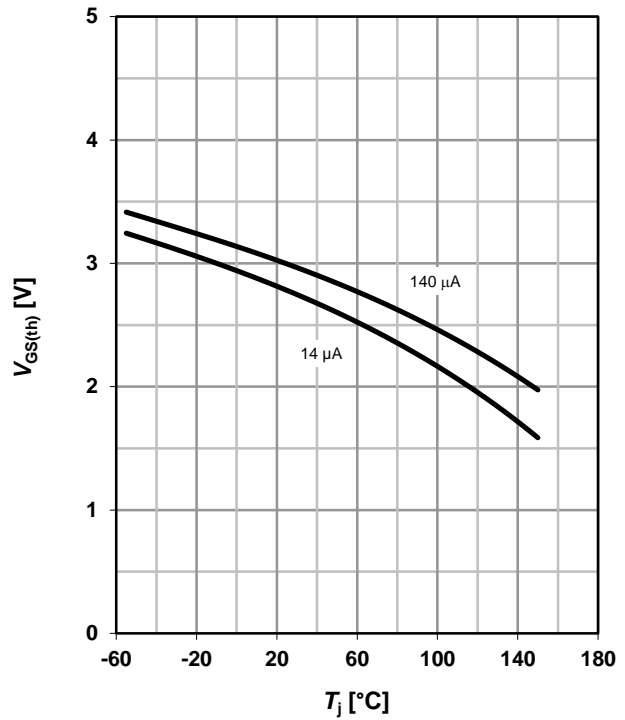
9 Drain-source on-state resistance

$R_{DS(on)}=f(T_j); I_D=40\text{ A}; V_{GS}=10\text{ V}$



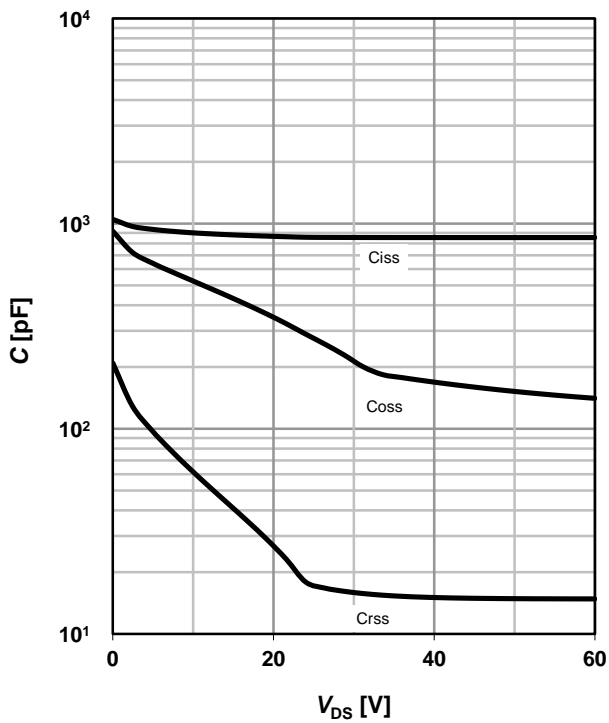
10 Typ. gate threshold voltage

$V_{GS(th)}=f(T_j); V_{GS}=V_{DS}$



11 Typ. capacitances

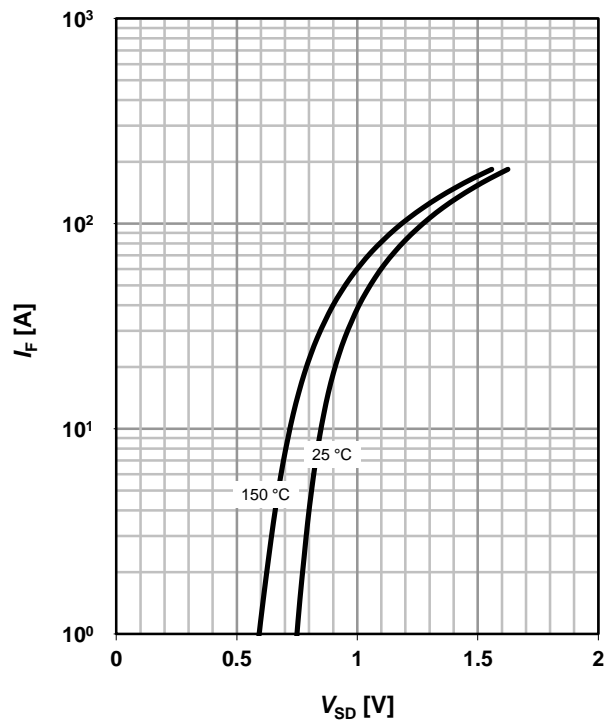
$C=f(V_{DS}); V_{GS}=0\text{ V}; f=1\text{ MHz}$



12 Forward characteristics of reverse diode

$I_F=f(V_{SD})$

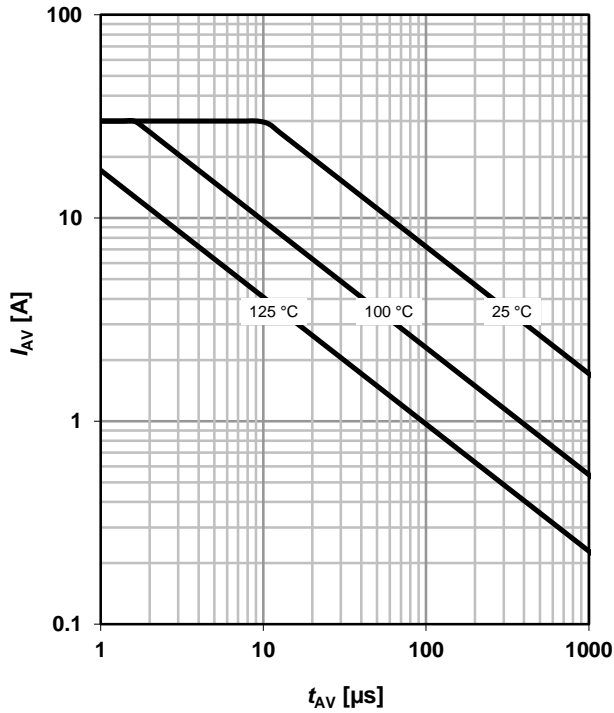
parameter: T_j



13 Avalanche characteristics

$I_{AS}=f(t_{AV}); R_{GS}=25 \Omega$

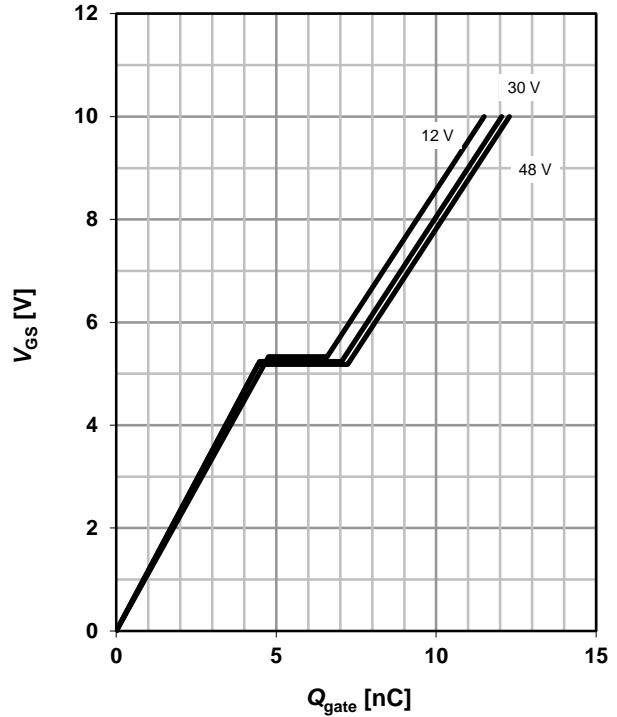
parameter: $T_{j(\text{start})}$



14 Typ. gate charge

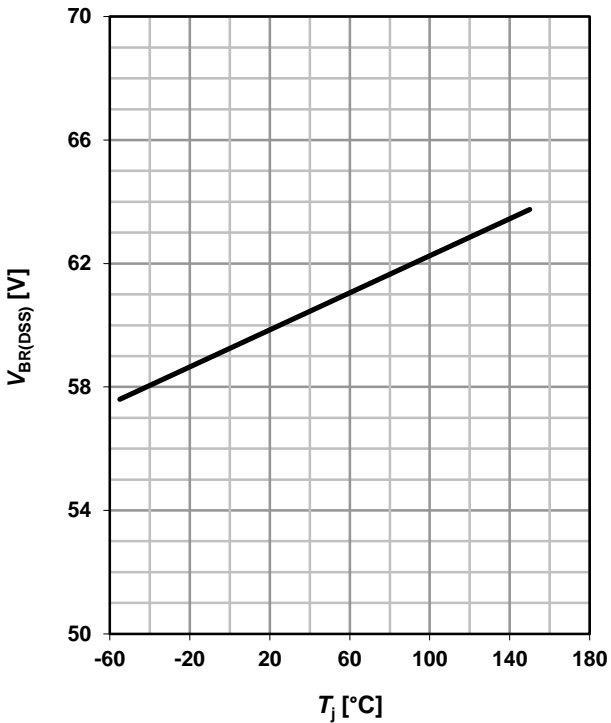
$V_{GS}=f(Q_{\text{gate}}); I_D=40 \text{ A pulsed}$

parameter: V_{DD}



15 Drain-source breakdown voltage

$V_{BR(DSS)}=f(T_j); I_D=1 \text{ mA}$



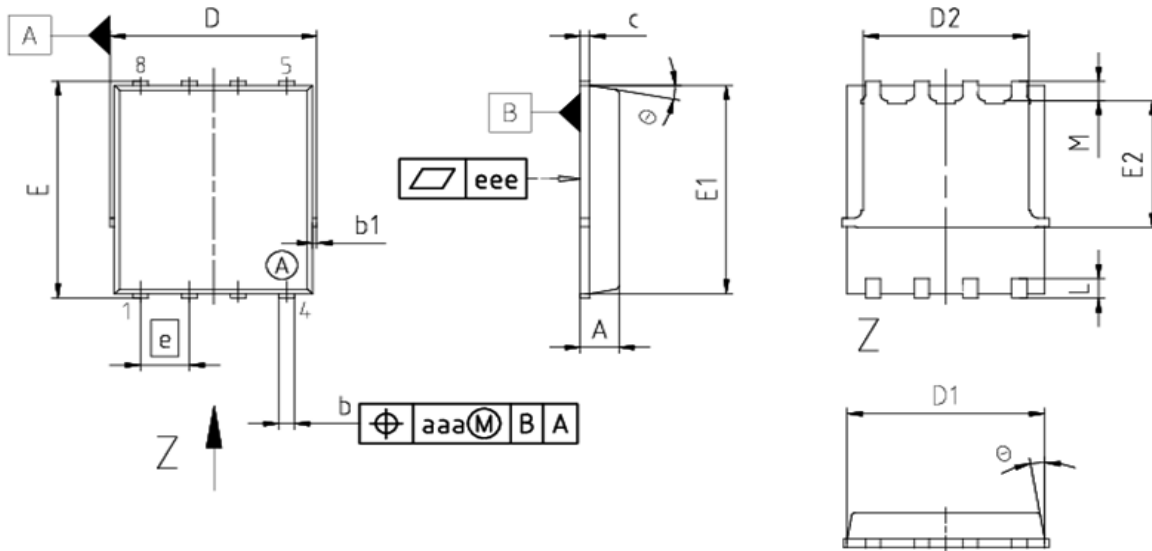
16 Gate charge waveforms



Package Outline

PG-TDSON-8

PG-TDSON-8: Outline



| DIM | MILLIMETERS | |
|-------|-------------|------|
| | MIN | MAX |
| A | 0.90 | 1.10 |
| b | 0.31 | 0.54 |
| b1 | 0.02 | 0.22 |
| c | 0.15 | 0.35 |
| D | 5.15 | 5.49 |
| D1 | 4.95 | 5.35 |
| D2 | 3.70 | 4.40 |
| E | 5.95 | 6.35 |
| E1 | 5.70 | 6.10 |
| E2 | 3.40 | 3.80 |
| e | 1.27 | |
| N | 8 | |
| L | 0.45 | 0.71 |
| M | 0.45 | 0.75 |
| theta | 8.5° | 12° |
| aaa | 0.25 | |
| eee | 0.08 | |

DOCUMENT NO.
Z8B00003332

SCALE

EUROPEAN PROJECTION

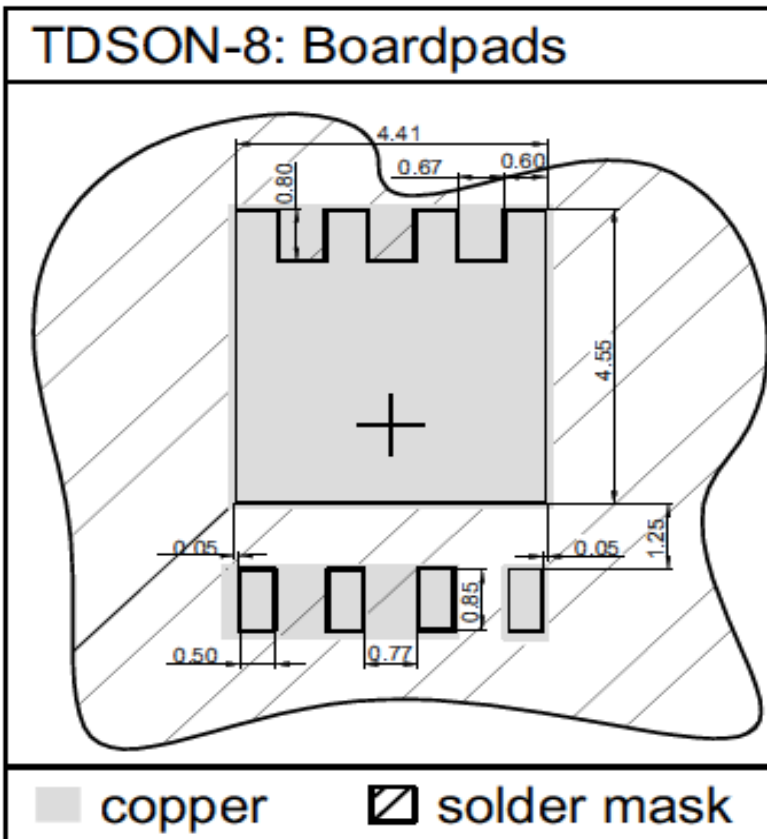
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04

Package Footprint

PG-TDSON-8

PG-TDSON-8: Footprint



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